Process Optimization on Advanced Al Wirebond Tools

Speaker: **Matthew Kurtz** - Rochester Electronics, Newburyport, MA

E-Mail: mkurtz@rocelec.com

Abstract

With the newest generations of Al wire bonders on the market, new setup parameters have been added to allow for more advanced and reliable wire bonds. These additional process variables can make process optimization difficult. Power, force, time, and loop height are no longer the only tools available to process reliability. In this presentation example results will be presented showing the methodology used to optimize a wire bond process on a Hesse BJ820 at Rochester Electronics in Newburyport, MA. A review of the main process effects of power, time, and force on pull strength will be reviewed. In addition, a study of more advance process parameters effect on bond quality will be undertaken.